



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-01
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	21GG*MV6DAAE	A	MA1A	2015-10-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	9.0	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	2x 2x1	12	No lead	
Comment	Package: A0XS LGA 2X2X1 12LD PITCH 0.5MM; MDF valid for LSM303AGRTR			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	21GG*MV6DAAE									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	3.015	mg	supplier	die	Silicon (Si)	7440-21-3		2.617	mg	867993	290778				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.017	mg	5638	1889				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.022	mg	7297	2444				
				supplier	metallisation	Iron (Fe)	7439-89-6		0.020	mg	6633	2222				
				supplier	metallisation	Nickel (Ni)	7440-02-0		0.022	mg	7297	2444				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.008	mg	2653	889				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.003	mg	995	333				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.011	mg	3648	1222				
				supplier	passivation	Silicon Oxide	7631-86-9		0.150	mg	49751	16667				
				JLG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.145	mg	48093	16111				
				substrate	Other Organic Materials	1.416	mg	supplier	core material	Fiber glass	65997-17-3		0.211	mg	149060	23444
								supplier	core material	Bisphenol F type epoxy resin	9003-36-5		0.118	mg	83361	13111
								supplier	core material	Bismaleimide (B)	105391-33-1		0.072	mg	50864	8000
supplier	core material	Triazine (T)	25722-66-1						0.072	mg	50864	8000				
supplier	core material	metal hydroxide	21645-51-2						0.005	mg	3532	556				
supplier	core material	Zinc hydroxyde	20427-58-1						0.001	mg	706	111				
supplier	core material	Calcium sulfate	7778-18-9						0.002	mg	1413	222				
supplier	Solder mask	Barium sulfate	7727-43-7						0.012	mg	8477	1333				
supplier	Solder mask	Acrylic resin	9003-01-4						0.018	mg	12716	2000				
supplier	Solder mask	Epoxy resin	29690-82-2						0.014	mg	9890	1556				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.009	mg	6358	1000				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.007	mg	4945	778				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.002	mg	1413	222				
supplier	Solder mask	Amorphous silica	7631-86-9						0.001	mg	706	111				
supplier	Solder mask	3-methyl-methoxy-buthyl	103429-90-9						0.001	mg	706	111				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.001	mg	706	111				
supplier	metallisation	Copper (Cu)	7440-50-8						0.859	mg	606735	95428				
supplier	metallisation	Nickel (Ni)	7440-02-0						0.008	mg	5934	933				
supplier	metallisation	Gold (Au)	7440-57-5						0.001	mg	805	127				
supplier	metallisation	Palladium (Pd)	7440-05-3						0.001	mg	805	127				
Die attach	Other inorganic materials	0.278	mg					supplier	tape	epoxy resin	Proprietary		0.176	mg	633094	19556
				supplier	tape	polyolefin	9003-07-0		0.088	mg	316547	9778				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.014	mg	50360	1556				
Die attach 2	Other inorganic materials	0.041	mg	supplier	tape	amorphous silica	7631-86-9		0.017	mg	414634	1889				
				supplier	tape	epoxy resin	25038-59-9		0.010	mg	243902	1111				
				supplier	tape	Acrylic resin	9003-01-4		0.007	mg	170732	778				
				supplier	tape	Epoxyde Bisphenol A Resin	25068-38-6		0.007	mg	170732	778				
Bonding wire	Precious metals	0.225	mg	supplier	wire	Gold (Au)	7440-57-5		0.223	mg	991111	24778				
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	8889	222				
encapsulation	Other Organic Materials	4.025	mg	supplier	mold compound	Silica, vitreous	60676-86-0		3.199	mg	794783	355444				
				supplier	mold compound	Silica	7631-86-9		0.403	mg	100124	44778				
				supplier	mold compound	Epoxy Resin	Proprietary		0.161	mg	40000	17889				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.141	mg	35031	15667				
				supplier	mold compound	Phenol Resin	Proprietary		0.101	mg	25093	11222				
supplier	mold compound	Carbon black	1333-86-4		0.020	mg	4969	2222								